

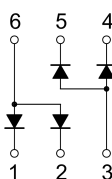
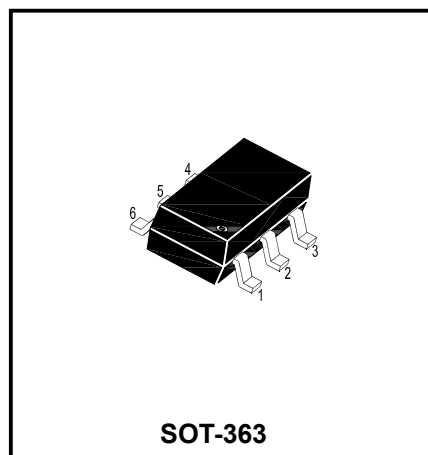
Plastic-Encapsulate Diodes

SCHOTTKY BARRIER DIODE ARRAYS

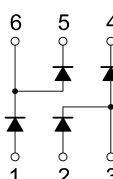
FEATURES

- ◆ Low Forward Voltage Drop
- ◆ Fast Switching
- ◆ Small Surface Mount Package
- ◆ PN Junction Guard Ring for Transient and ESD Protection
- ◆ Available in Lead Free Version

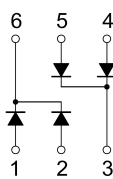
MARKING:



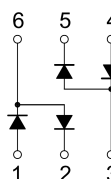
BAT54ADW



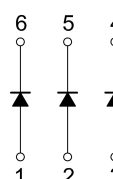
BAT54BRW



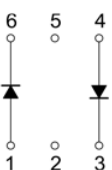
BAT54CDW



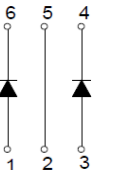
BAT54SDW



BAT54TW



BAT54DW



BAT54JW

BAT54ADW	BAT54BRW	BAT54CDW	BAT54SDW	BAT54TW

BAT54DW	BAT54JW

Solid dot = Green molding compound device, if none, the normal device.

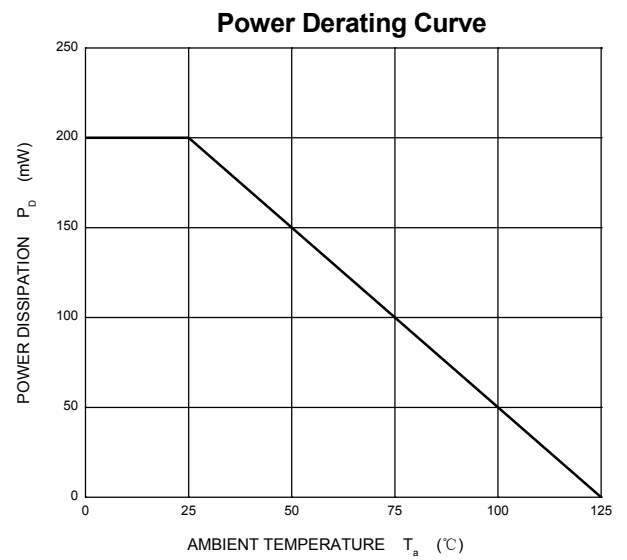
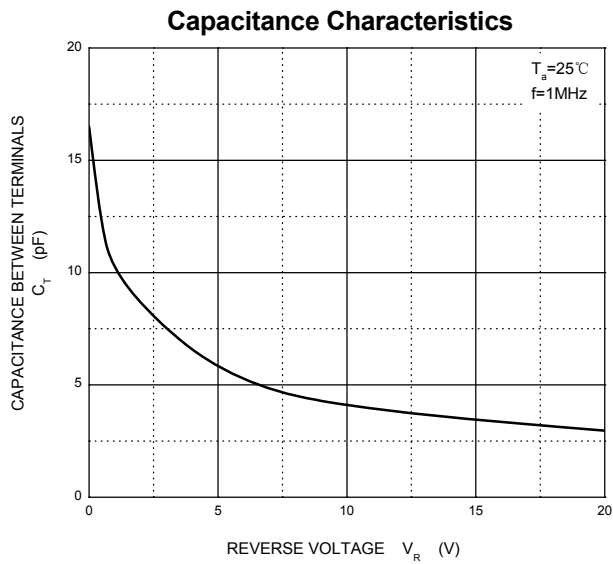
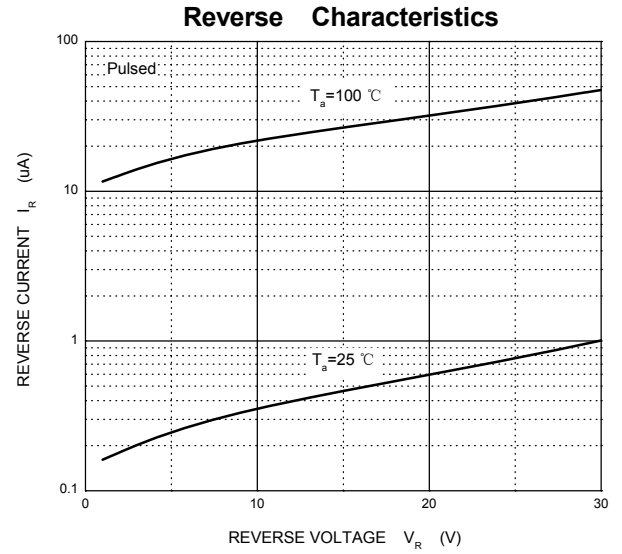
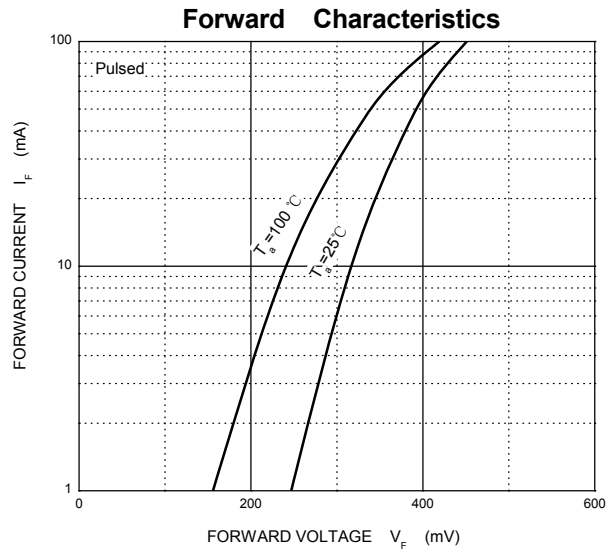
ELECTRICAL CHARACTERISTICS
MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	30	V
V_{RWM}	Peak Working Reverse Voltage		
V_R	DC Blocking Voltage		
I_O	Forward Continuous Current	200	mA
I_{FRM}	Repetitive Peak Forward Current	300	mA
I_{FSM}	Non-repetitive Peak Forward Surge Current @t=8.3ms	600	
P_D	Power Dissipation	200	mW
$R_{\theta JA}$	Thermal Resistance From Junction To Ambient	500	°C/W
T_j	Junction Temperature	125	°C
T_{stg}	Storage Temperature	-55~+150	°C

ELECTRICAL CHARACTERISTICS (T =25°C unless otherwise specified)

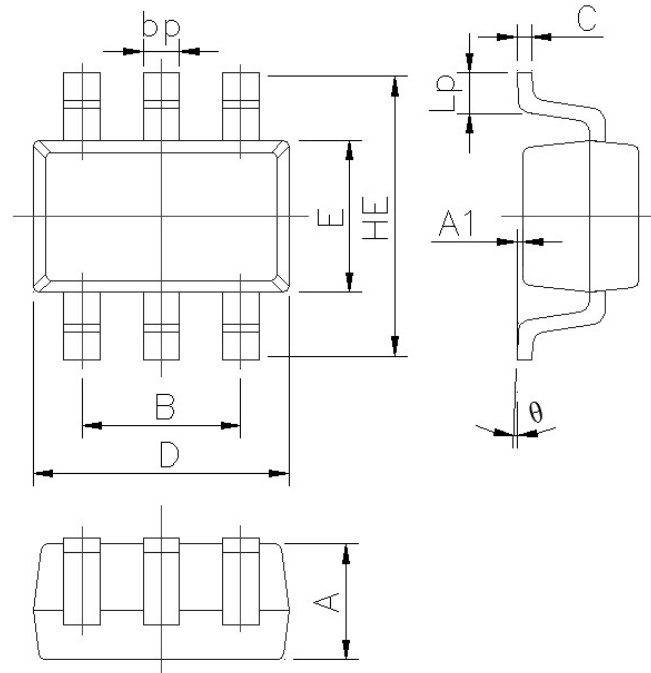
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse voltage	$V_{(BR)}$	$I_R=100\mu A$	30			V
Reverse current	I_R	$V_R=25V$			2	μA
Forward voltage	V_F	$I_F=1mA$			320	mV
		$I_F=10mA$			400	
		$I_F=30mA$			500	
		$I_F=100mA$			1000	
Total capacitance	C_{tot}	$V_R=1V, f=1MHz$			15	pF
Reverse recovery time	t_{rr}	$I_F=I_R=10mA, I_{rr}=0.1\times I_R, R_L=100\Omega$			5	ns

Typical Characteristics



Package Outline

SOT-363



Symbol	Dimension in Millimeters	
	Min	Max
A	0.90	1.00
A1	0.010	0.100
B	1.20	1.40
bp	0.25	0.45
C	0.09	0.15
D	2.00	2.20
E	1.15	1.35
HE	2.15	2.55
Lp	0.25	0.46
θ	0°	6°

Summary of Packing Options

Package	Package Description	Packing Quantity	Industry Standard
SOT-363	Tape/Reel, 7" reel	3000	EIA-481-1